

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)  
 Contact Info: [ti.com/support](http://ti.com/support)  
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB  
 Created on: 06/13/2022

Details for "UCC2800DG4"

**Current Product Information**

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package   Pins	Package body size (mm)	Total device mass (mg)*
UCC2800DG4	NIPDAU	Level-1-260C-UNLIM	TI AGUASCALIENTES	D   8	3.91x4.9x1.58	84.5

**\*Total Device Mass**

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

**Environmental Ratings Information**

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

**Component Information**

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
<b>Bond Wire</b>							
Copper and Its Alloys	Copper	7440-50-8	0.069958	99.998571	999986	0.082801	828
Precious Metals	Silver	7440-22-4	0.000001	0.001429	14	0.000001	0
Sub-Total			0.069959	100	1000000	0.082802	828
<b>Die Attach Adhesive</b>							
Precious Metals	Silver	7440-22-4	0.511032	78.999994	790000	0.604846	6048
Thermoplastics	Epoxy	85954-11-6	0.135844	21.000006	210000	0.160782	1608
Sub-Total			0.646876	100	1000000	0.765628	7656
<b>Lead Frame</b>							
Copper and Its Alloys	Copper	7440-50-8	24.025981	97.425003	974250	28.436632	284366
Copper and Its Alloys	Iron	7439-89-6	0.591864	2.4	24000	0.700517	7005
Copper and Its Alloys	Phosphorus	7723-14-0	0.003699	0.014999	150	0.004378	44
Copper and Its Alloys	Tin	7440-31-5	0.007398	0.029999	300	0.008756	88
Copper and Its Alloys	Zinc	7440-66-6	0.024661	0.1	1000	0.029188	292
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.007398	0.029999	300	0.008756	88
Sub-Total			24.661001	100	1000000	29.188228	291882
<b>Lead Frame Plating</b>							
Nickel and Its Alloys	Nickel	7440-02-0	0.037097	95.120513	951205	0.043907	439
Precious Metals	Gold	7440-57-5	0.000304	0.779487	7795	0.00036	4
Precious Metals	Palladium	7440-05-3	0.001599	4.1	41000	0.001893	19
Sub-Total			0.039	100	1000000	0.04616	462
<b>Mold Compound</b>							
Other Inorganic Materials	Fused Silica	60676-86-0	49.913897	87.999999	880000	59.077011	590770
Other Plastics and Rubber	Carbon Black	1333-86-4	0.170161	0.3	3000	0.201399	2014
Other Plastics and Rubber	Organic Phosphorus	1330-78-5	0.311962	0.55	5500	0.369231	3692
Thermoplastics	Epoxy	85954-11-6	6.324318	11.150001	111500	7.485326	74853
Sub-Total			56.720338	100	1000000	67.132967	671330
<b>Semiconductor Device</b>							
Ceramics / Glass	Doped Silicon	7440-21-3	2.35237	100	1000000	2.784214	27842
Sub-Total			2.35237	100	1000000	2.784214	27842
<b>Total</b>			84.489544			100	1000000

**Important Note**

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component. The ppm calculations are for the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component. See [Glossary of Terms for more details](#).

**Important Part Information**

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSLs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

**Product Content Methodology**

For an explanation of the methods used to determine material weights, see [Product Content Methodology](#).

**Material Declaration Certificate for Semiconductor IC Packaged Products**

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

**Important Information/Disclaimer**

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is." For additional information, please contact [TI customer support](#).

Signature: [\(click here for a fuller statement with a signed certificate\)](#)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality  
 For further environmental statements, please go to [www.ti.com/ecoinfo](http://www.ti.com/ecoinfo)  
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**RoHS:** Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

**RoHS Exempt:** Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szq088>

**Green:** Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.